

ABSTRACT

The present invention provides an improved structure of gold fingers, which is to redesign a conventional gold finger on a packaging substrate into a gold finger set that contains a plurality of gold finger units. Between each single gold finger unit, there exists an electrical connection. Therefore, in the structure of stacked-chip packaging, each wire that is connected through wire bonding on the same gold finger of each layer chip can separately perform wire bonding on different gold finger units of the same gold finger set. Due to the improvement on the gold finger structure, the present invention can prevent the adhesive on a chip from flowing along the wire bonding path of a layer chip and smearing the whole gold finger. Thus, other layer chips can be prevented from being unable to perform wire bonding.